



Japanese Unexamined Patent Application,

First Publication No. S61-198798

Applicant: Sony Corporation

[Abstract]

[Object]

The objects of the present invention are to simplify a connecting work which connects a plurality of fabric flexible substrates having a conductive portion with each other, and to enable the connecting work at any place. The objects are achieved by stacking predetermined parts of the conductive portions of the fabric flexible substrates and sewing the parts together with a conductive thread so as to provide conduction therebetween.

[Constitution]

A fabric flexible substrate 2 is laid on another fabric flexible substrate 1 in such a manner that a conductive portion 2a of the fabric flexible substrate 2 overlaps with a predetermined part of a conductive portion 1a of the fabric flexible substrate 1, and the overlapped part is sewed together with a conductive thread 3 with a sewing machine. Thus, the conductive portions 1a and 2a are connected with each other, and the fabric flexible substrates 1 and 2 are connected and fixed with each other.